

描述 / Descriptions

SOT23-3 塑封封装 低压差线性稳压器。
Low dropout linear regulator in a SOT23-3 Plastic Package .

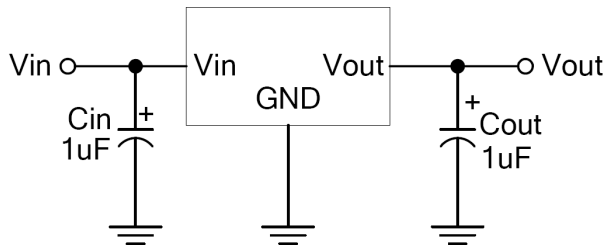
特点 / Features

- ◆ Maximum Output Current: 250mA
- ◆ Dropout Voltage: 200mV ($I_{OUT} = 100mA$)
- ◆ Maximum Operating Voltage: 7V
- ◆ Fixed Output Voltage: 1.5V, 1.8V , 2.8V, 3.0V and 3.3V.
- ◆ Low Power Consumption: TYP 4 μ A
- ◆ Operating Temperature e Range: -40 $^{\circ}$ C~+80 $^{\circ}$ C
- ◆ Halogen-free Product.

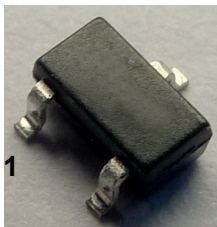
应用 / Applications

- ◆ Battery-powered equipment
- ◆ Palmtops, Notebook Computers
- ◆ Hand-held Instruments
- ◆ PCMCIA Cards

应用电路 / Typical Application



引脚排列 / Pinning



PIN 1 : GND PIN 2 : VOUT PIN 3 : VIN

印章代码 / Marking

见印章说明。 See Marking Instructions.

绝对最大额定值 / Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Rating	Unit
Input Voltage	V _{IN}	7	V
Power Dissipation	P _D	0.4	W
Operating junction temperature	T _{opr}	-40~+80	°C
Storage temperature	T _{stg}	-65~+150	°C
Package Thermal Resistance(note1)	R _{θJA}	250	°C/W

电性能参数 / Electrical Characteristics(V_{IN}=5.5V, C_{IN}=1μF, C_{OUT}T=1μF, T_A=25°C, unless otherwise specified)

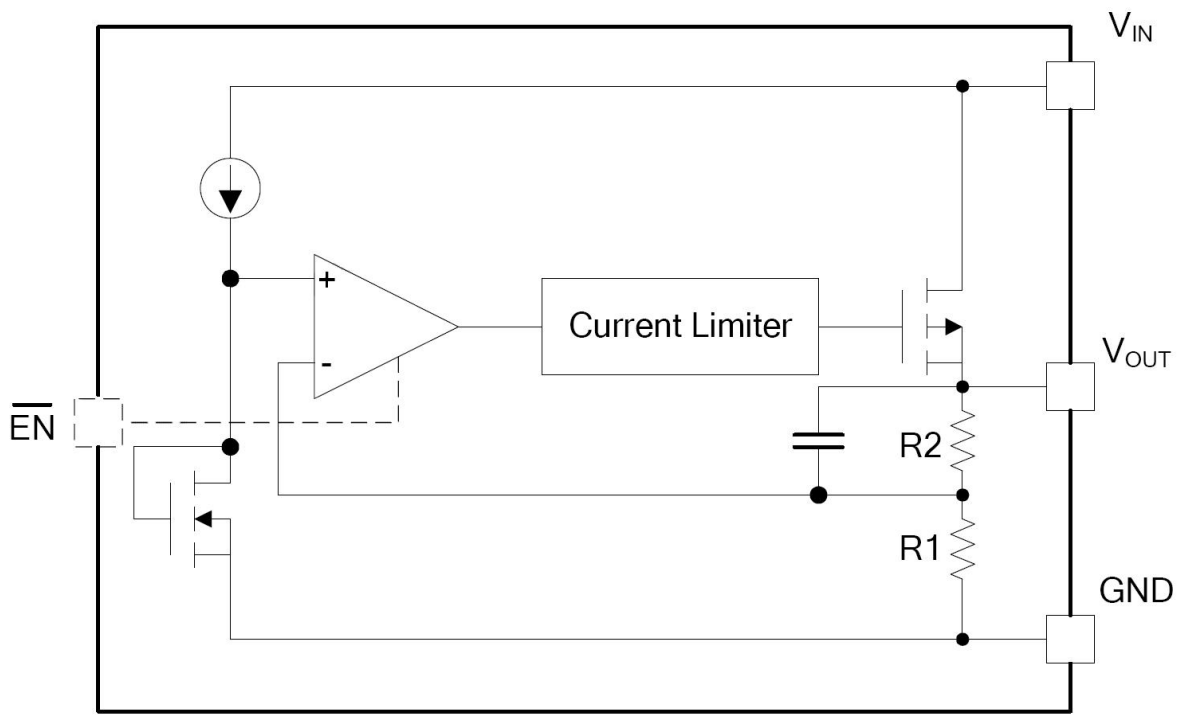
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Output Voltage	V _{out}	I _L =1mA, V _{IN} = V _{out} (note2)+1V	×0.98	V _{out} (note2)	×1.02	V
Maximum Output Current	I _{MAX}	V _{IN} = V _{OUT} T+0.6V, V _{IN} ≥3.6V	100	250		mA
Current Limit	I _{LIM}	I _L =100mA	150			mA
GND Pin Current	I _G	No Load		4.0	7.0	μA
		I _{out} =100mA		4.0	10	
Dropout Voltage	V _{DROP}	I _{out} =1mA, V _{IN} ≥3.6V		4.0	10	mV
		I _{out} =50mA, V _{IN} ≥3.6V		200	300	
		I _{out} =100mA, V _{IN} ≥3.6V		450	600	
Line Regulation	ΔV _{LINE}	V _{IN} =(V _{OUT} +0.3V) to 6V V _{IN} ≥3.6V, I _{out} =1mA	-0.2		+0.2	%/V
Load Regulation	ΔV _{LOAD}	I _L OUT=0mA to 100mA		0.01	0.04	%/mA
Output Noise	e _{NO}	BW=100Hz to 50kHz C _{OUT} =10μF		250		μV
Ripple Rejection	PSRR	F=1kHz, C _{OUT} =1μF		30		dB
EN Threshold			0.6	1.0	2.0	V
Thermal Shutdown Protection			150			°C

Note:

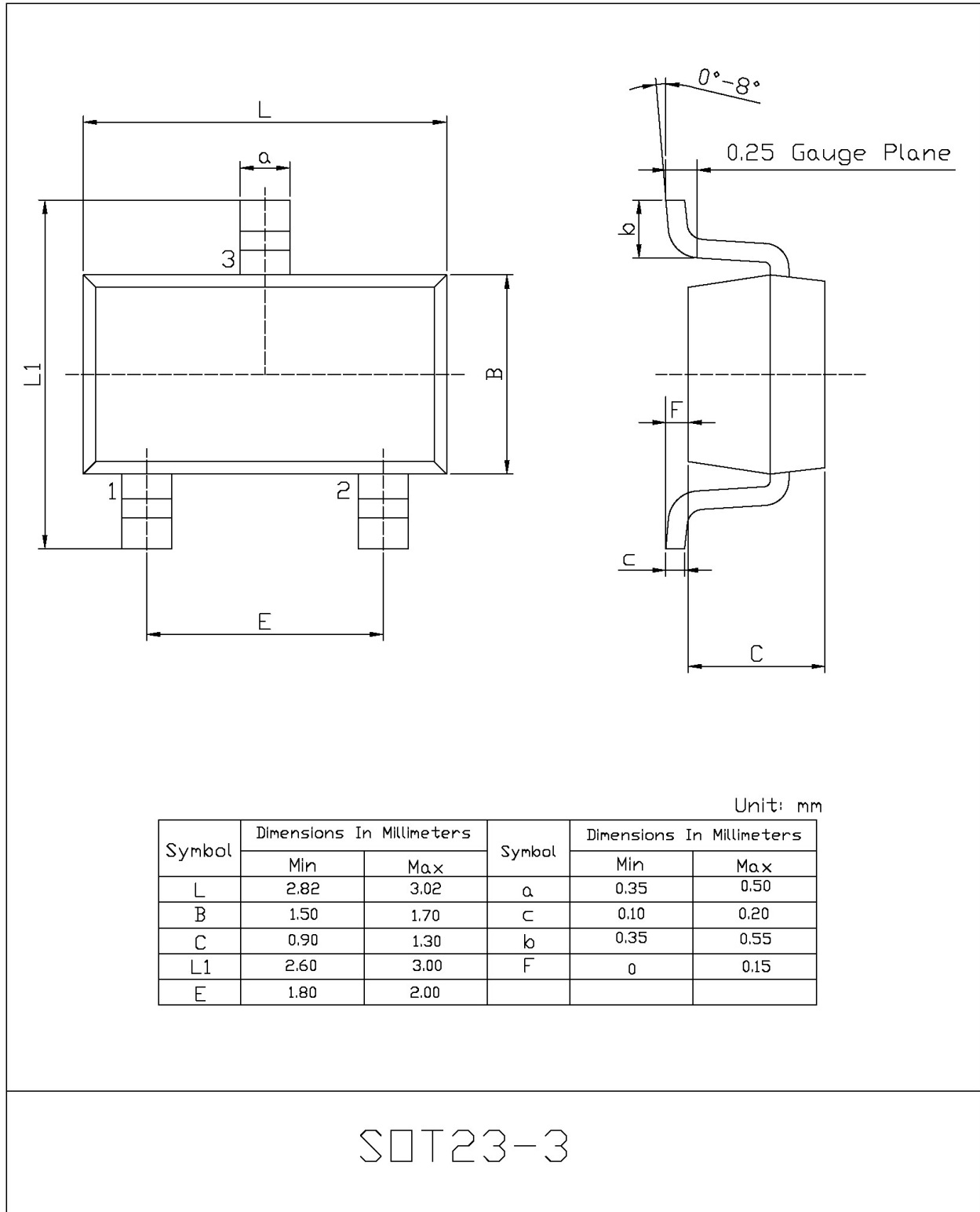
1) R_{θJA} is measured in the natural convection at T_A = 25°C on a low effective thermal conductivity test board of JEDEC 51-3 thermal measurement standard.

2) V_{out}: Nominal V_{out}

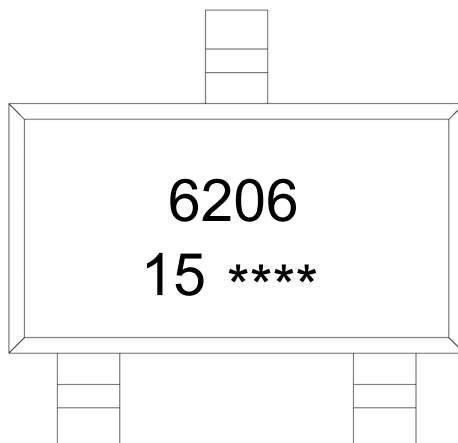
结构图 / Block Diagram



外形尺寸图 / Package Dimensions



印章说明 / Marking Instructions



说明：

6206：为产品型号代码

15：输出电压代码

****：生产批次代码

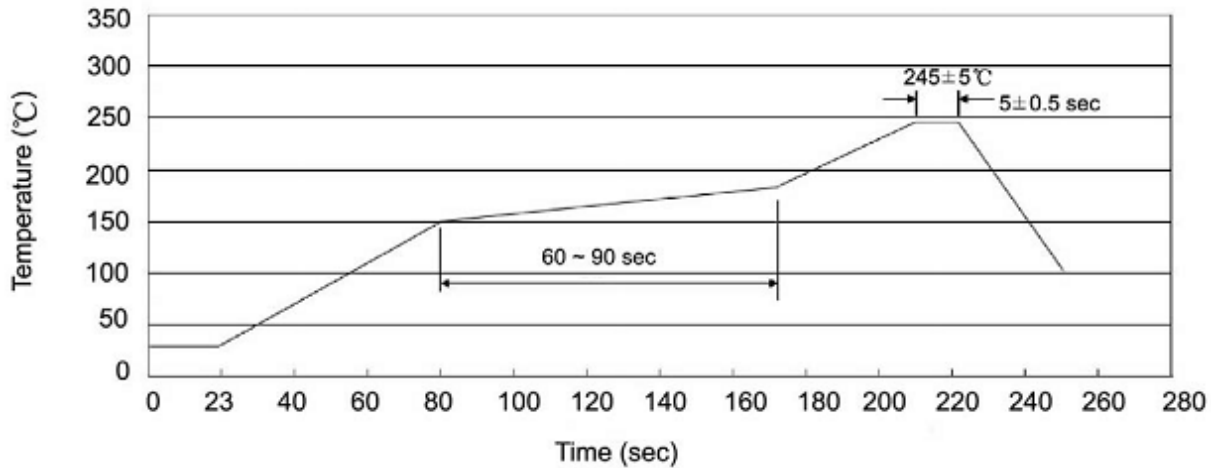
Note:

6206: Product Type Code.

15: V_{out} Code.

****: Lot No. Code, code change with Lot No.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec；
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec；
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23-3	3,000	10	30,000	4	120,000	7" ×8	210×205×205	445×230×435

使用说明 / Notices